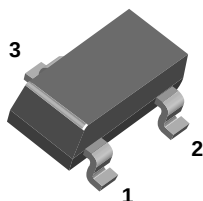
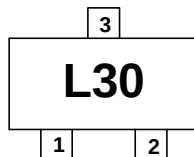


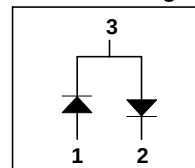
BAV23S



SOT-23



Connection Diagram



Small Signal Diode

Absolute Maximum Ratings* T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Maximum Repetitive Reverse Voltage	250	V
I _{F(AV)}	Average Rectified Forward Current	200	mA
I _{FSM}	Non-repetitive Peak Forward Surge Current	9.0	A
	Pulse Width = 1.0 microsecond	3.0	A
	Pulse Width = 100 microsecond		
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _J	Operating Junction Temperature	150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
P _D	Power Dissipation	350	mW
R _{θJA}	Thermal Resistance, Junction to Ambient	357	°C/W

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
V _R	Breakdown Voltage	I _R = 100 μA	250		V
V _F	Forward Voltage	I _F = 100 mA		1.0	V
		I _F = 200 mA		1.25	V
I _R	Reverse Current	V _R = 250 V V _R = 250 V, T _A = 150°C		100 100	nA μA
t _{rr}	Reverse Recovery Time	I _F = I _R = 30 mA, I _{RR} = 3.0 mA, R _L = 100 Ω		50	ns

Typical Characteristics

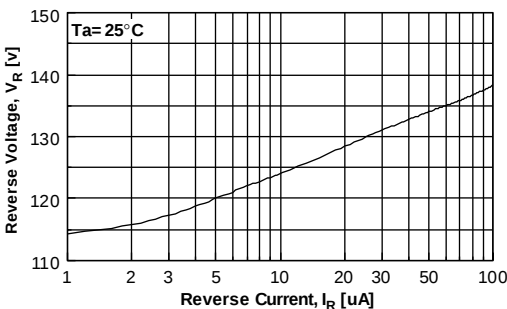


Figure 1. Reverse Voltage vs Reverse Current
BV - 1.0 to 100 μA

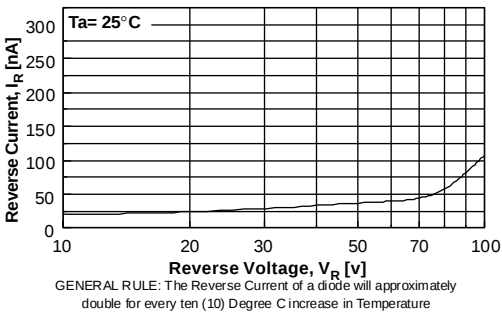


Figure 2. Reverse Current vs Reverse Voltage
 I_R - 10 to 100 V

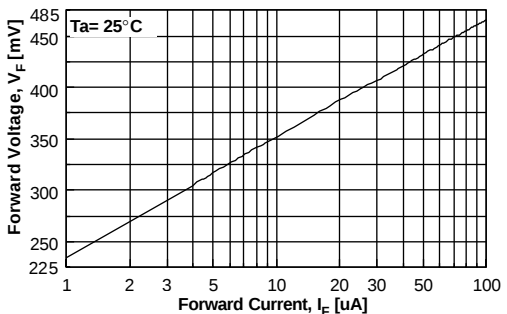


Figure 3. Forward Voltage vs Forward Current
VF - 1.0 to 100 μA

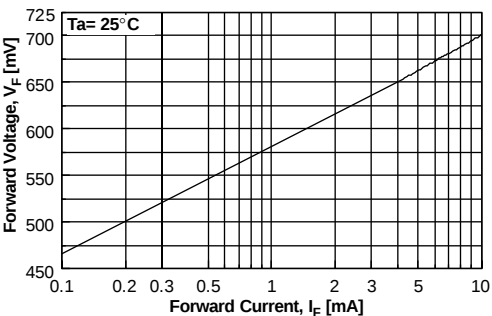


Figure 4. Forward Voltage vs Forward Current
VF - 0.1 to 10 mA

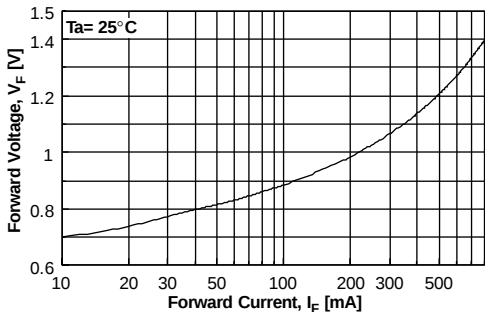


Figure 5. Forward Voltage vs Forward Current
VF - 10 - 800 mA

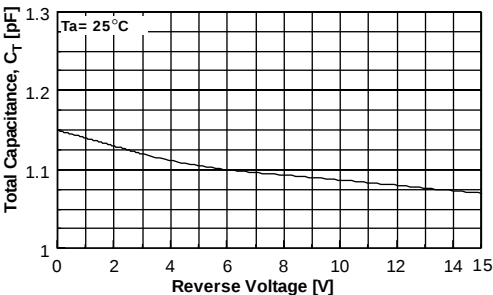


Figure 6. Total Capacitance

Typical Characteristics (continued)

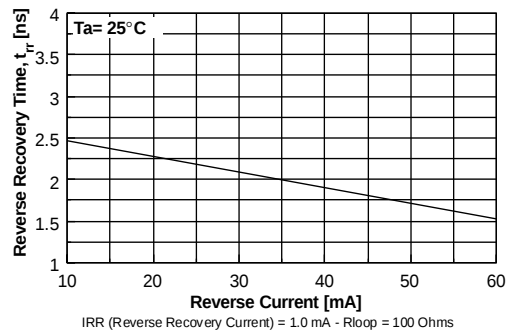


Figure 7. Reverse Recovery Time
vs Reverse Current
TRR - IR 10 mA vs 60 mA

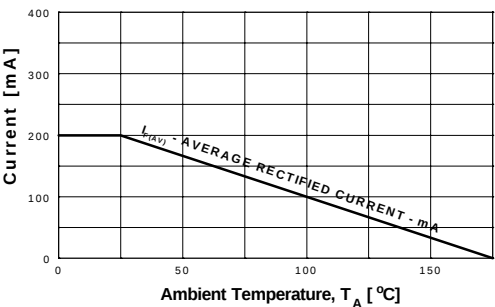


Figure 8. Average Rectified Current ($I_{F(AV)}$)
versus Ambient Temperature (T_A)

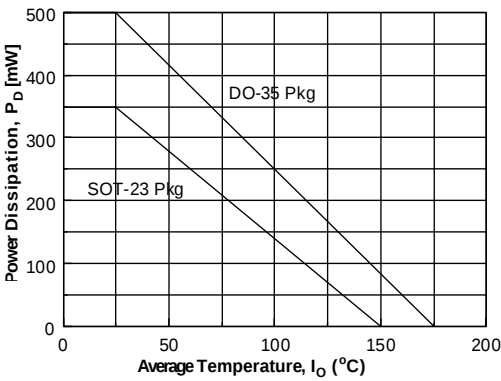


Figure 9. Power Derating Curve

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